

Connector for Memory Stick™

SCEC Series

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ESD (electro-static discharge) protection model whose robust structure achieves high reliability.

For SD Memory Card

For microSD™ Card

For SIM Card 8pins

For W-SIM

For Memory Stick Micro™

For Memory Stick™

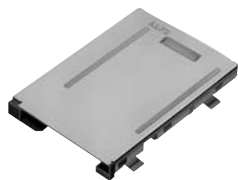
Combine Type

For Compact Flash™

For PC cards supporting CardBus

For Express Card™

For CMOS Camera Module



Features

- Improved operability from long ejection stroke (10mm) and clear click feel.
- 4 solder lug terminals are provided in the plate for secure mounting onto the PC board.
- Allows setting of media locking mechanism.
- Reflow solderable.

Applications

- For compact audio equipment, personal digital assistants, desktop PCs and notebook PCs
- For home audio equipment (TVs, set top boxes and recorders)
- For digital camcorders, digital still cameras, and headphone players

Typical Specifications

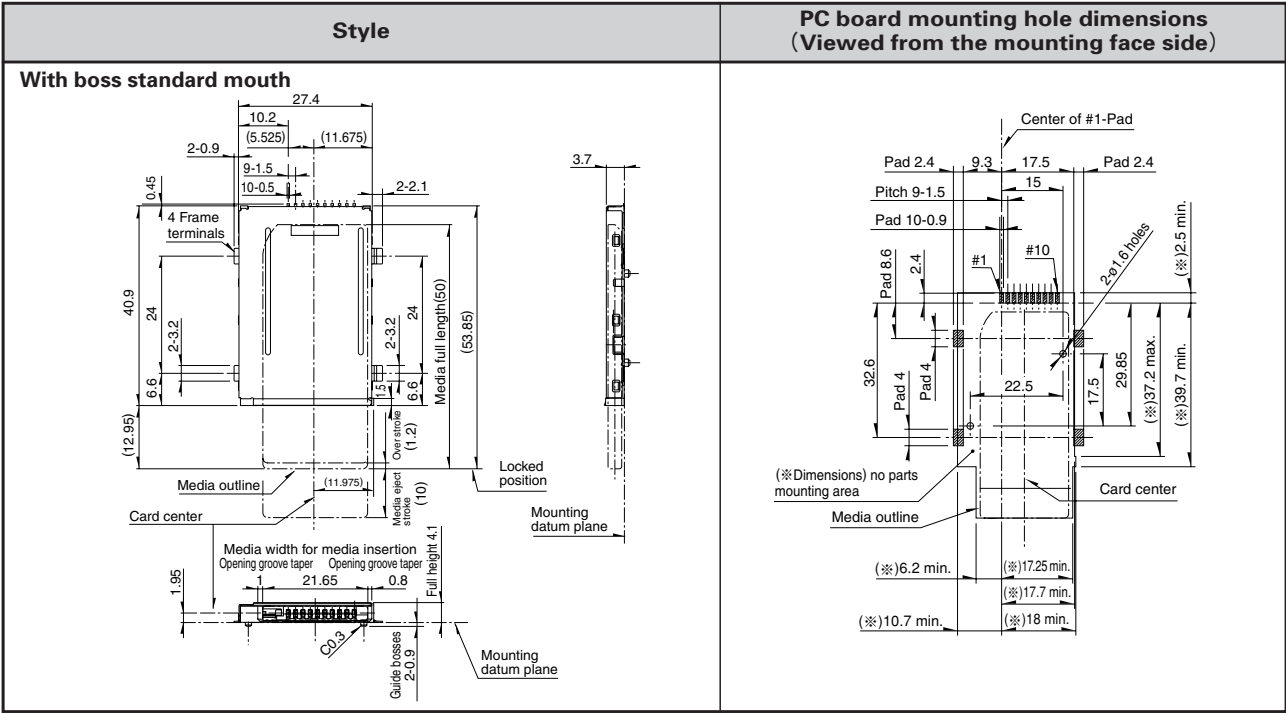
Items		Specifications
Structure	Applicable media	Memory Stick™
	Mounting type	Surface mounting type
	Mounting style	Standard mount
	Media ejection structure	Push-push type
Performance	Operating temperature range	−20℃ to +60℃
	Voltage proof	500V AC 1minute
	Insulation resistance (Initial)	1,000MΩ min.
	Contact resistance (Initial)	40mΩ max.
	Insertion and removal cycle	12,000cycles

Product Line

Media ejection structure	Mounting system	Features	Stand-off (mm)	Packing system	Product No.
Push-push type	Standard mount	With boss standard mouth	0	Tray	SCEC1B0100

Dimensions

Unit:mm



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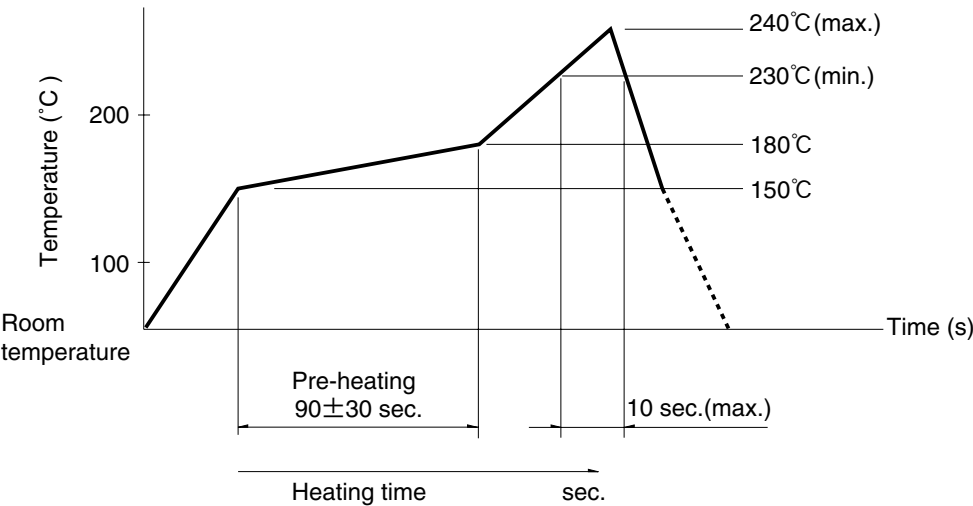
For Express Card™

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Soldering Conditions

Example of Reflow Soldering Condition (Reference)

- 1. Heating method: Double heating method with infrared heater.
- 2. Temperature measurement: Thermocouple 0.1 to 0.2 ϕ CA (K) or CC (T) .
- 3. Temperature profile (Surface of products) .



Cautions for using this product

- 1. When soldering terminals, there is a danger that load placed on the terminals may cause rattle, deformation or electrical degradation to occur depending on the conditions. Caution is therefore required.
- 2. Avoid use of water-soluble soldering flux, since it may corrode the product.
- 3. Check and conform to reflow soldering requirements under actual mass production conditions.
- 4. PC board warping may alter the characteristics. Please take this into consideration when designing patterns and layout.
- 5. The card specifications are provided by the above manufactures. Products by other manufactures may not be compliant with these specifications and are subject to change without prior notice.